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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HVU200A

Variable Capacitance Diode for Electronic Tuning



ADE-208-067D(Z)

Rev. 4
Jun. 1996

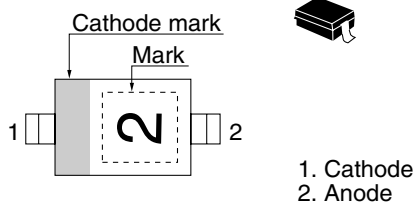
Features

- High capacitance ratio($n = 10\text{min}$) and suitable for wide band tuner.
- Ultra small Resin Package (URP) is suitable for surface mount design.
- Low series resistance and good C-V linearity.

Ordering Information

Type No.	Laser Mark	Package Code
HVU200A	2	URP

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	32	V
Junction temperature	T_J	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I_{R1}	—	—	10	nA	$V_R = 30V$
	I_{R2}	—	—	100		$V_R = 30V, T_a = 60\text{ }^{\circ}C$
Capacitance	C_2	27.7	—	31.8	pF	$V_R = 2V, f = 1\text{ MHz}$
	C_{25}	2.67	—	3.03		$V_R = 25V, f = 1\text{ MHz}$
Capacitance ratio	n	10.0	—	—	—	C_2 / C_{25}
Series resistance	r_s	—	—	0.70	Ω	$V_R = 5V, f = 470\text{ MHz}$
Matching error	$\Delta C/C^{-1}$	—	—	2.0	%	$V_R = 2\text{ to }25V, f = 1\text{ MHz}$

Note: 1. C.C system (Continuous Connected taping system) enable to make any 10 pcs of $\Delta C/C$ continuous in a reel , expect extention to another group.
Calculate Matching Error,

(Cmax-Cmin)

$$\Delta C/C = \frac{\text{Cmax-Cmin}}{\text{Cmin}} \times 100 (\%)$$

Main Characteristic

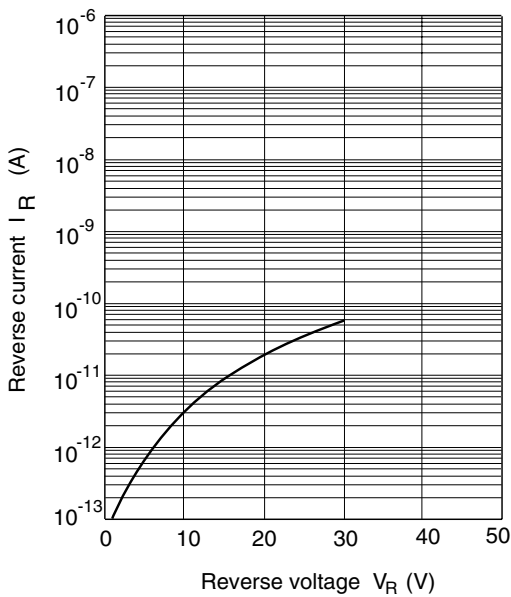


Fig.1 Reverse current Vs. Reverse voltage

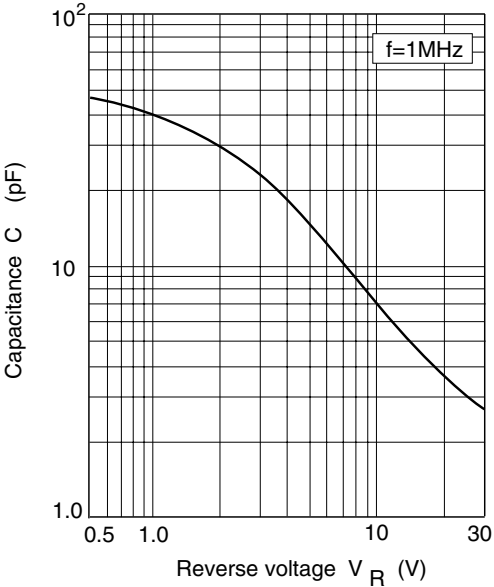


Fig.2 Capacitance Vs. Reverse voltage

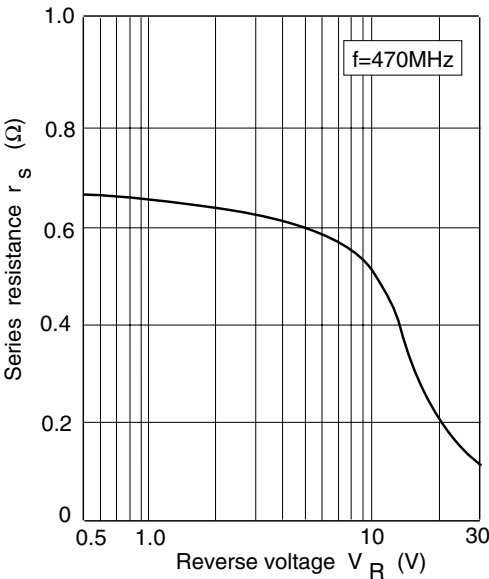


Fig.3 Series resistance Vs. Reverse voltage

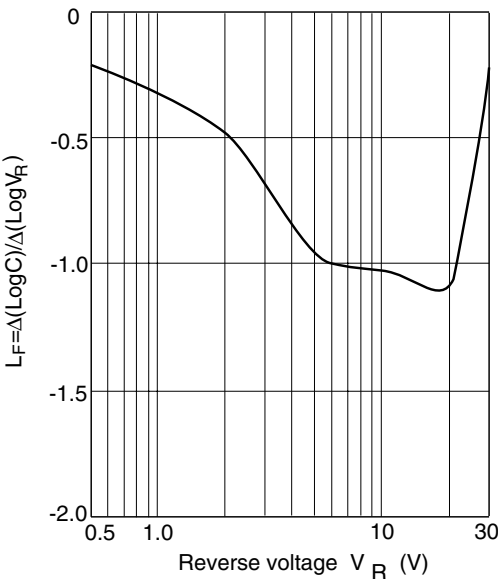
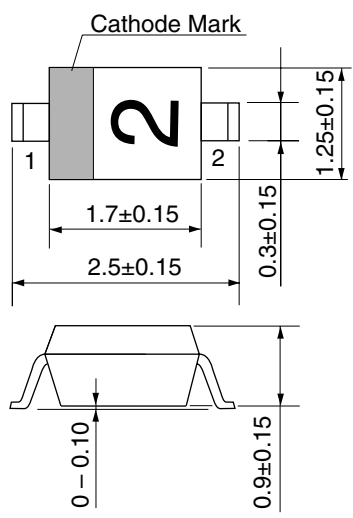


Fig.4 Linearity factor Vs. Reverse voltage

Package Dimensions

Unit : mm



- 1. Cathode
- 2. Anode

Hitachi Code	URP
JEDECCode	—
EIAJCode	—
Weight(g)	0.004

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